



Special Issue Film Materials and Devices

Call for Papers

Thin films are fabricated by the deposition of individual atoms on a substrate. Thin film materials and devices are also available for minimization of toxic materials since the quantity used is limited only to the surface and/or thin film layer. Thin film processing also saves on energy consumption in production and is considered an environmentally benign material technology for the next century. The goal of this special issue is to provide a platform for scientists and academicians all over the world to promote, share, and discuss various new issues and developments in the area of **film materials and devices**.

In this special issue, we invite front-line researchers and authors to submit original research and review articles that explore **film materials and devices**. In this special issue, potential topics include, but are not limited to:

- Ceramic thin films
- Electronic film materials
- Thin film technology and deposition processes
- Structural control of compound thin films
- Properties of thin SiO₂ Layers
- Semiconductor thin film material
- Nanometer thin film materials
- Dielectric film materials

Authors should read over the journal's [For Authors](#) carefully before submission. Prospective authors should submit an electronic copy of their complete manuscript through the journal's [Paper Submission System](#).

Please kindly specify the “**Special Issue**” under your manuscript title. The research field “**Special Issue –Film Materials and Devices**” should be selected during your submission.

Special Issue timetable:

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|---------------------|-------------------|
| Submission Deadline | August 20th, 2020 |
| Publication Date | October 2020 |

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For further questions or inquiries
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